REMARKS

After consideration of the documents cited in the International Search Report, and of the International Preliminary Examination Report, we have modified the set of claims as shown above. Modifications are supported by the description:

- claims 15 and 29 supported by page 10, lines 24-25, page 11, lines 19-20, and lines 24-26,
- claim 30 supported by page 11, lines 22-23,
- claim 31 supported by page 11, lines 21-22 and page 8, lines 28-29,
- claim 32 supported by page 11, lines 31-32

The claimed invention is protecting an optoelectronic connector comprising a package comprising an optical port, an electrical port, and a bare control and emission-detection integrated circuit chip. The integrated circuit chip is directly connected to metallized connections made in an internal wall of the package of the connector. More specifically the disclosed embodiment is an optoelectronic connector comprising laser diodes being transferred on the integrated circuit. The transfer of the diodes is made through at least two steps.

First diodes are laid out on an intermediate support, and then they are transferred on the integrated circuit. To be correctly disposed on the intermediate support, diodes may be firstly laid out on a gallium arsenide substrate.

They are then presented on the integrated circuit, and not on a substrate of printed circuit board type, neither on a connector's package type.

It is a feature of the disclosed embodiments to present a higher miniaturisation optoelectronic connector (Page 1, line 27, "With a view to minaturisation"). The problem solved by the invention is clearly explained in the description (page 10, line 27-31 and page 11, lines 8-18).

Respectfully submitted,

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